



Semiconductor Device Type: CB / NB / TT (C6X) 003 SOT-23 Matte Tin			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			JEDEC 97 Product Marking and/or Pkg. Labeling e3	
Basic Substance	CAS Number	Contained in Sub-Component	% Total Weight	mg/part	ppm	6.62	(mg) Total	Mold Compound	% of Total Weight	79.8
Silica, vitreous	60676-86-0	Mold Compound	67.830	5.630	678,300		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin (No bromine, No diantimony trioxide)	Trade Secret	Mold Compound	4.888	0.406	48,878		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin (No Br / CL SbO3, No diantimony trioxide)	Trade Secret	Mold Compound	4.888	0.406	48,878		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.955	0.162	19,551		Epoxy, Cresol Novolac	29690-82-2	2.45	
Carbon Black	1333-86-4	Mold Compound	0.239	0.020	2,394		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	10.031	0.833	100,314		Total 100.00			
Iron	7439-89-6	Lead Frame	0.247	0.020	2,468	0.87	(mg) Total	Lead Frame	% of Total Weight	10.5
Silver	7440-22-4	Lead Frame	0.200	0.017	2,000		Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.013	0.001	131		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.009	0.001	87		Silver	7440-22-4	1.91	
Silver (Ag)	7440-22-4	Die Attach	0.563	0.047	5,625		Zinc	7440-66-6	0.13	
Modified Epoxy Resin	13561-08-5	Die Attach	0.105	0.009	1,050		Phosphorous	7723-14-0	0.08	
Diglycidylether of bisphenol-F	54208-63-8	Die Attach	0.056	0.005	563		Total 100.00			
Modified Amine	827-43-0	Die Attach	0.026	0.002	263	0.06	(mg) Total	Die Attach	% of Total Weight	0.75
Silicon	7440-21-3	Chip (Die)	7.500	0.623	75,000		Silver (Ag)	7440-22-4	75.00	
Gold	7440-57-5	Wire Bond	0.200	0.017	2,000		Modified Epoxy Resin	13561-08-5	14.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	0.104	12,500		Diglycidylether of bisphenol-F	54208-63-8	7.50	
TOTALS:			100.000	8.300	1,000,000		Modified Amine	827-43-0	3.50	
0.0083 g Total Mass							Total 100.00			
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)										
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.										
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.										
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL IQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/										
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table										
						0.62	Total (mg)	Chip (Die)	% of Total Weight	7.5
							Doped Silicon	7440-21-3	100.00	
						Total 100.00				
						0.02	(mg) Total	Wire Bond	% of Total Weight	0.2
							Doped Gold	7440-57-5	100.00	
						Total 100.00				
						0.10	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.25
							Tin	7440-31-5	100.00	
						Total 100.00				
						8.300				100.000